



TWSE STOCK CODE 1560



1Q25 Investor Conference

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Disclaimers

- The prospective statements released or mentioned in this presentation are based on our company's data as well as the current situation.
- The forward-looking statements contained in this presentation are affected by risks, uncertainties, and people's inferences. As a result, actual results may differ materially from those in the forward-looking statements. There are various factors that can affect our prospective statements, including but not limited to the increasing cost of raw materials, market demands, changes of policies or financial situations, and risks that our company cannot control.
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Outline

- Welcome
 - William Lee, DBU President/Spokesperson
 - Tony Pai, Vice President/Acting Spokesperson
- Company overview
- 1Q25 financial results
- 2025 outlook
- Q & A
- Appendix: KINIK Visions/Missions, Products, Plants information



Company Overview

- Company established in 1953; Taiwan Stock Code 1560
- Capital : 1,463 Million(TWD) (Mar. 31 2025)
- Employees : ~2400 worldwide. (~1800 in Taiwan.)
- 2024 revenue 7,019M TWD, EPS=7.1
- Main products by 3 BUs & subsidiaries, and Sales Ratio in 2024

Product
Introduction



ABU: Abrasives BU

Subsidiaries: KTC & Hongia

Sales Ratio: 18%



Grinding wheel
(Machinery & Mechanical
Indus.)

DBU: Diamond BU

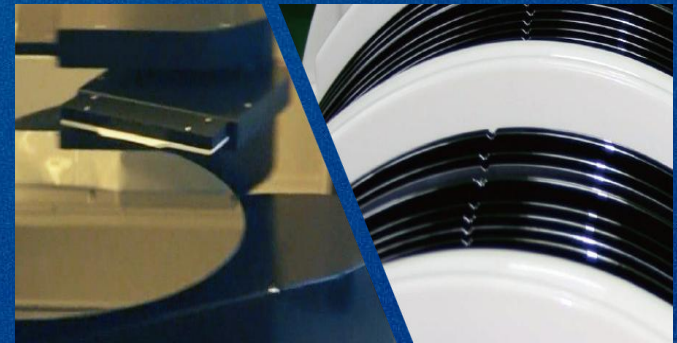
32%



CMP Diamond Disk
(Semiconductor Indus.)

SBU: Semiconductor Material BU

50%



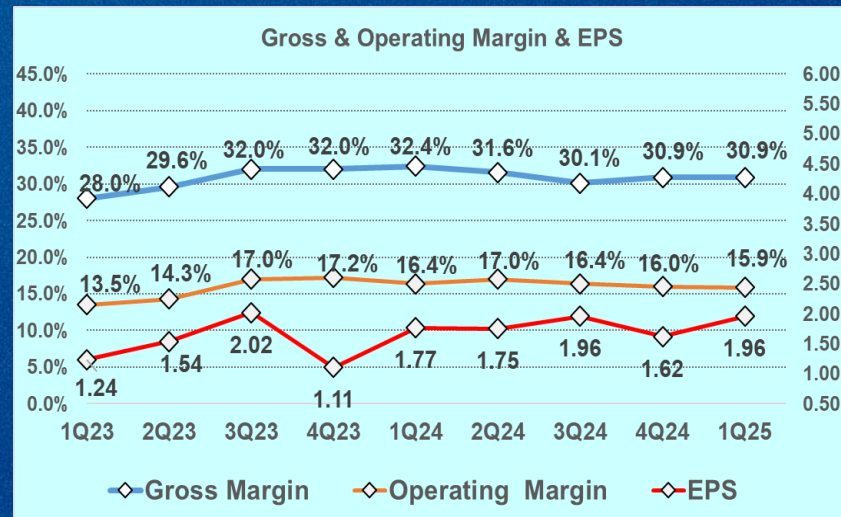
Reclaim & Test Si Wafer
(Semiconductor Indus.)



1Q25 Consolidated Income statement

- 1Q25 consolidated revenue: NTD 1.77 billion, QoQ -3.4%, YoY +11.1%. Gross margin: 30.9% (+0ppt); EPS: 1.96.
- FX impact: NT dollar depreciation led to FX gains of ~NTD 32 million, up ~NTD 2 million QoQ.

Accounting Period Income (all in thousands TWD except *)	1Q25	4Q24	1Q25 over 4Q24	1Q24	1Q25 over 1Q24
*Net Revenue(USD thousand)	53,839	56,752	-5.1%	50,753	6.1%
Net Revenue	1,771,627	1,834,012	-3.4%	1,595,178	11.1%
Gross Margin	30.9%	30.9%	+0 ppt	32.4%	-1.5 ppt
Operating Expenses	(266,125)	(272,181)	-2.2%	(254,895)	4.4%
Operating Margin	15.9%	16.0%	-0.1 ppt	16.4%	-0.5 ppt
Non-Operating Items	33,794	13,223	20,571	59,876	(26,082)
Net Income to Shareholders of the Parent Company	285,815	239,295	19.4%	256,690	11.3%
Net Profit Margin	16.3%	13.6%	+2.7 ppt	16.9%	-0.6 ppt
EPS	1.96	1.62	21.0%	1.77	10.7%
ROE	15.8%	14.3%	+1.4 ppt	17.1%	-1.3 ppt
Average Exchange Rate-USD/NTD	32.91	32.32	1.8%	31.43	4.7%





1Q25 Sales Performance by BUs

ABU: Grinding Wheel

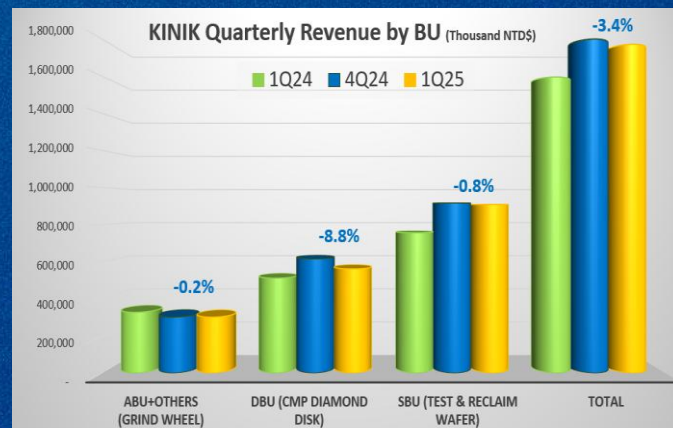
DBU: CMP Pad Conditioner

SBU: Reclaim Wafer

Others: Subsidiaries

- **Company-wide**: 1Q25 revenue of NTD 1.77 billion, QoQ -3.4%, YoY +11.1%.
- **ABU + Others**: Traditional industry customer demand slightly declined; electronics customer demand increased; revenue flat QoQ.
- **DBU**: Revenue down 8.8% QoQ due to earthquake impact on major customer production, and fewer working days in 1Q.
- **SBU**: Test wafer shipments declined, while reclaimed and specialty wafer shipments increased; revenue down 0.8% QoQ.

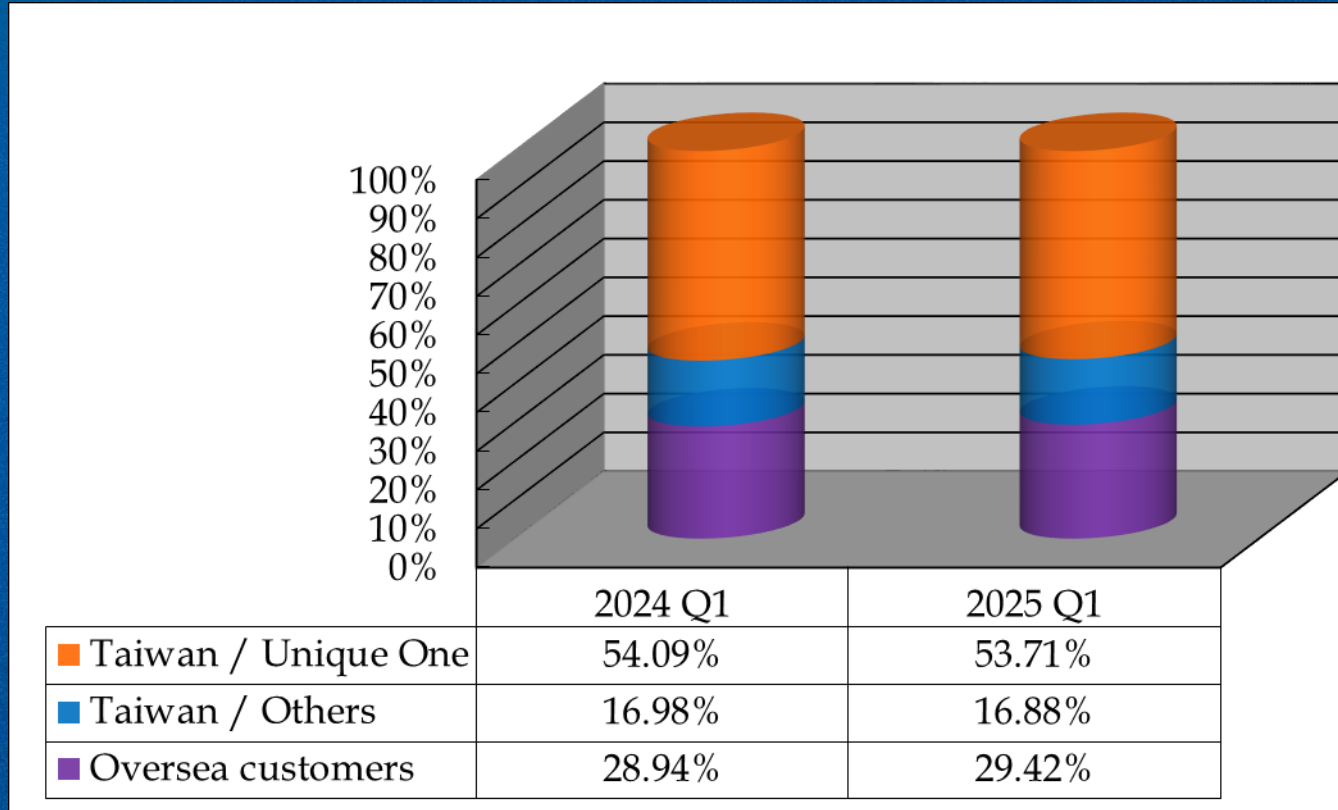
Business Unit	1Q24	4Q24	1Q25		QoQ	YoY
ABU+others (Grind Wheel)	327,463	302,011	301,322	17%	-0.2%	-8.0%
DBU (CMP Diamond Disk)	511,589	615,474	561,418	32%	-8.8%	9.7%
SBU (Test & Reclaim Wafer)	756,126	916,527	908,887	51%	-0.8%	20.2%
Total	1,595,178	1,834,012	1,771,627	100%	-3.4%	11.1%





1Q25 Diamond Disk Sales (1/2)

Diamond Disk Sales Ratio by Region

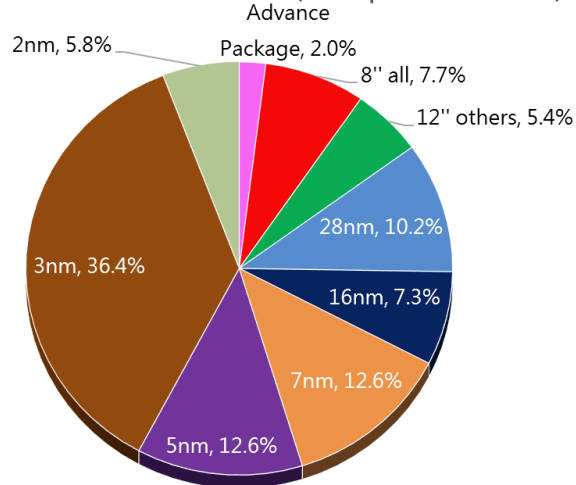




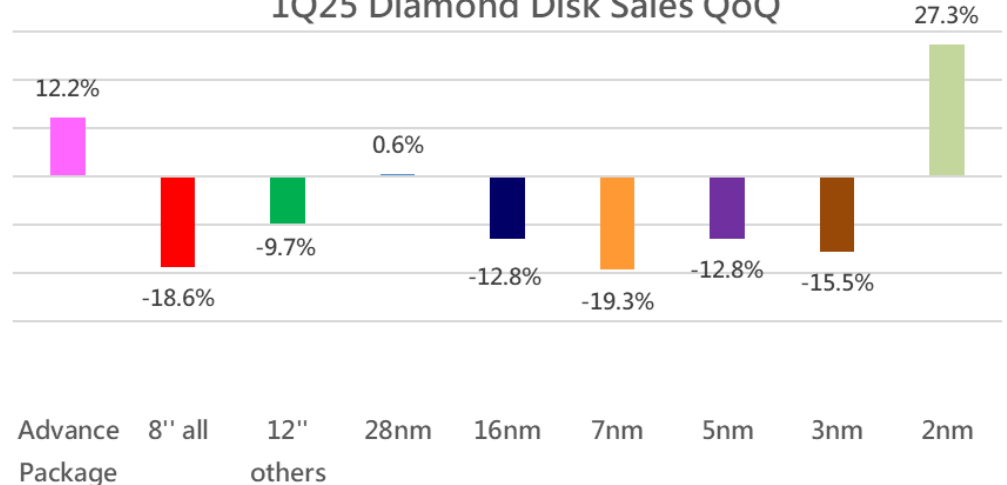
1Q25 Diamond Disk Sales (2/2)

- DBU revenue for 1Q25 was NTD 560 million, representing a QoQ decline of 8.8%, mainly due to production disruptions from the January earthquake affecting Taiwan customers and fewer working days in the first quarter.
- Revenue contribution from one specific customer's sub-5nm products remained stable at 54.8%; 2nm diamond disk sales increased by 27.3%.

1Q25 Diamond Disk Sales Ratio (one specific customer)



1Q25 Diamond Disk Sales QoQ



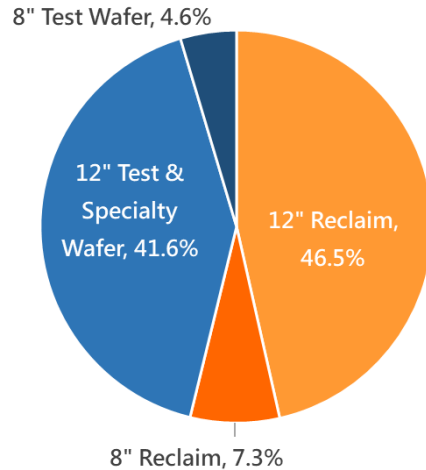
Remark : Data regards to one specific customer.



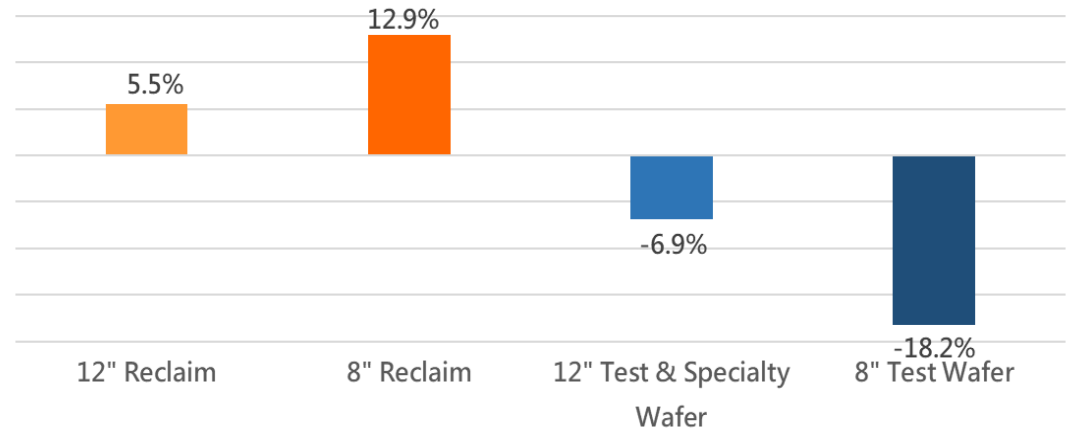
1Q25 SBU Wafer Sales

- SBU sales QoQ -0.8%
- Higher shipments of reclaimed and specialty wafers offset lower test wafer shipments, driving gross margin improvement.

1Q25 Wafer Type Sales Ratio



1Q24 SBU Wafer Sales QoQ





Summary of Recent Key Events

- ◆ On April 1, 2025, the Company successfully completed the acquisition of 100% equity interest in Mitsui Kensaku Toishi Co., Ltd. (MKS), a subsidiary of Japan's Mitsui Mining & Smelting Group, for a purchase price of JPY 1.919 billion. Additionally, the Company, together with its subsidiary KINIK Thai Company Limited, jointly acquired Mitsui Grinding Technology (Thailand) Co., Ltd. (MGT) from the same group for a purchase price of THB 450 million. The total consideration for the two acquisitions amounts to approximately NTD 836 million.
- ◆ In accordance with the Company's Employee Stock Option Plans for 2020 and 2022, a total of 318,800 shares were exercised between January 1, 2025 and March 31, 2025, raising a total of NTD 31,266,610. After the capital increase, the Company's paid-in capital amounted to NTD 1,462,692,340. The record date for the capital increase through the issuance of new shares for the first quarter of 2025 has been set for April 29, 2025.



2025 Outlook

- ◆ ABU Grinding Wheel Business Unit and Subsidiaries
 - 2025 industrial and machine tool demand to gradually recover.
 - High-end grinding wheel and ABF customer demand to increase.
 - Revenue contributions from MKS (Japan) and MGT (Thailand) start in April, thus full-year revenue of KINIK's grinding wheel sales are expected to grow significantly vs. 2024.
- ◆ DBU CMP Diamond Disk
 - Demand for diamond disks in advanced logic and memory continues to rise.
 - 2nm diamond disk shipments expected to grow quarterly.
 - Monthly capacity had expanded to 50,000 units to meet 2025 year-end possible max demand.
- ◆ SBU Reclaim/Test/Specialty Wafer:
 - Reclaimed and test wafer ASP to remain flat YoY in 2025.
 - 12-inch wafer capacity to reach 330K/month in 3Q25 and 400K/month in 3Q26.
 - Ongoing shift to high-end and specialty wafers to drive revenue and margin growth.

Q & A

Thanks for your attention

**KINIK's investor relationship mail:
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Appendix

- ◆ Company Philosophy, Mission, and Vision
- ◆ Introduction of KINIK Products
- ◆ Plants Information
- ◆ Company Milestone



KINIK Company

Business philosophy
Good together

Good to You, Me, All

經營
理念
共好

你好，我好，大家好

使
命

Mission

Keep creating innovative values
for industries and customers.

精益求精為產業
與客戶創新價值

Vision

願
景

成為研磨解決方案的
卓越智造與服務中心

Become an excellent and intelligent
smart manufacturing and service center
for grinding solutions.



History, Now, and Future of KINIK

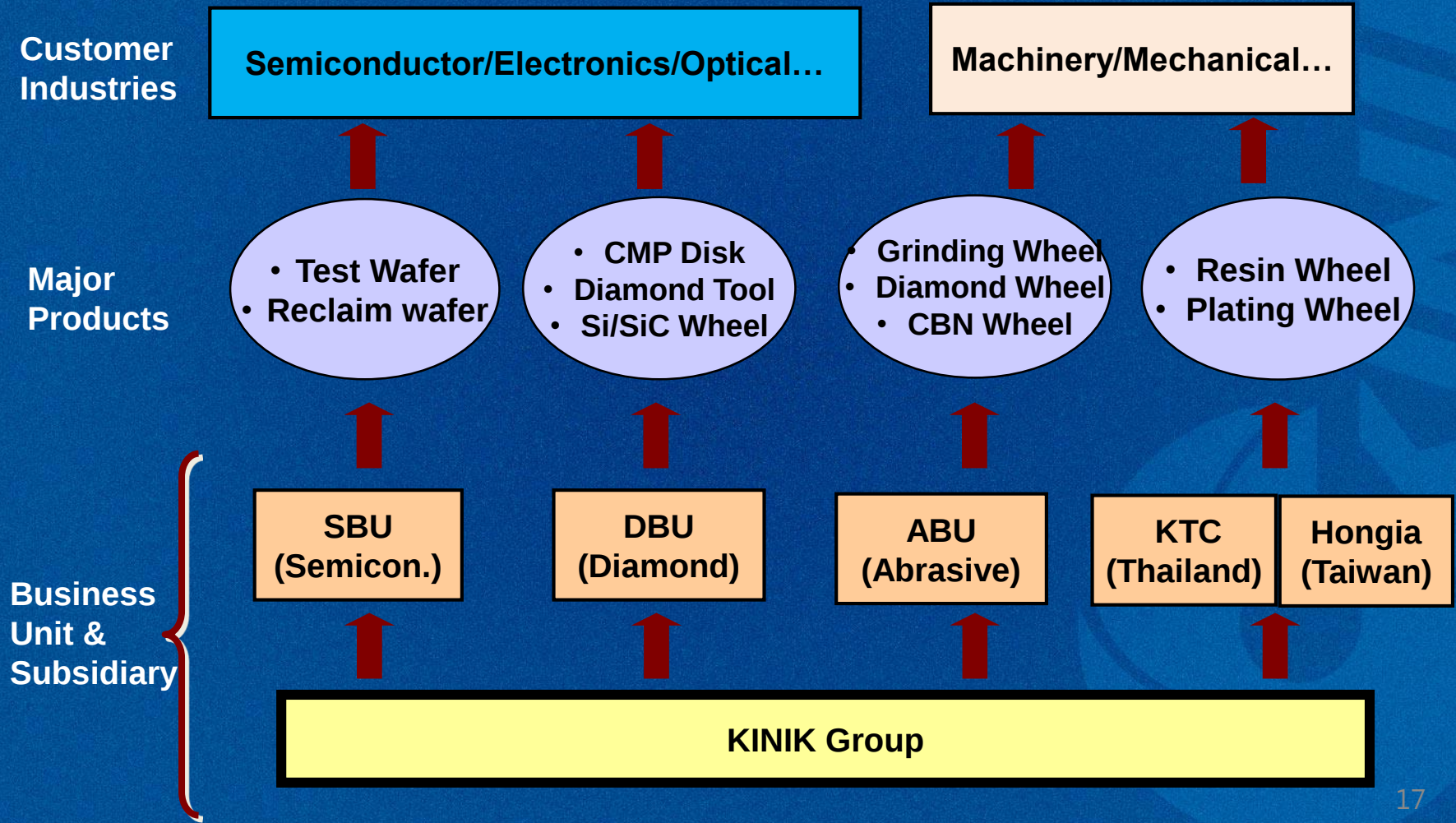




Core Technology “Grinding”



Major Product and Business Diagram



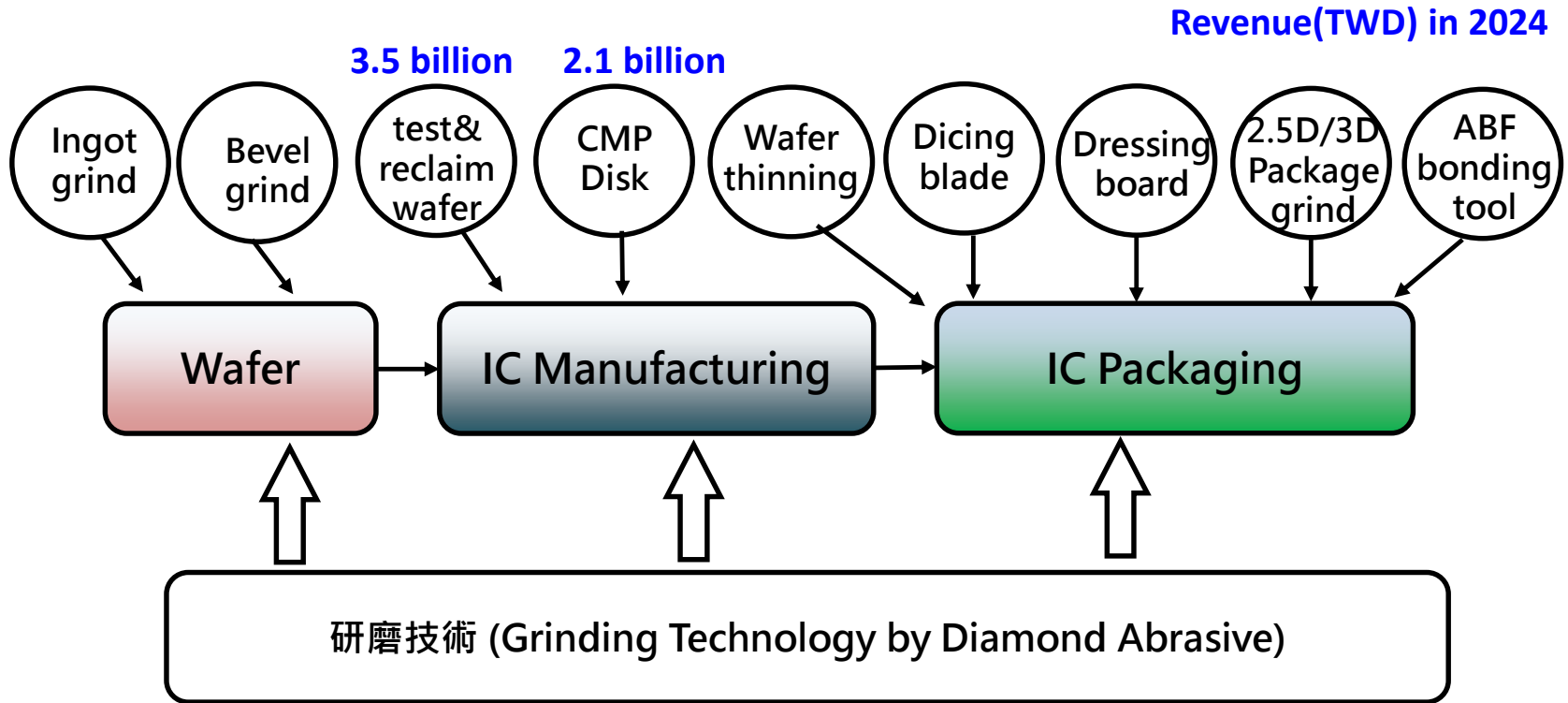


中砂產品介紹

Products Introduction



KINIK' s products in Semiconductor Industries



In 2024, revenue from semiconductor industries was 5.8 billion (82% of total)
The gross margin is 34%(3% higher than the total average (30.4%))

What is test and reclaim wafer?

The source of the reclaimed wafers comes from the monitor wafers and the dummy wafers but not the defect wafers manufactured by the semiconductor fab. The services we provide to refurbish these reclaimed wafers can dramatically lower the running cost of a semiconductor manufacturer.

The reclaimed wafers can be categorized according to functions as figure 1 and the reclamation system is shown as figure 2.

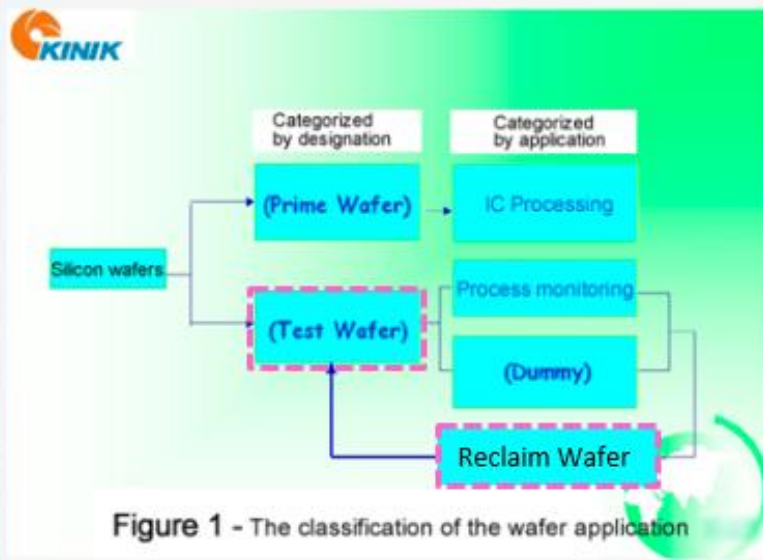


Figure 1 - The classification of the wafer application

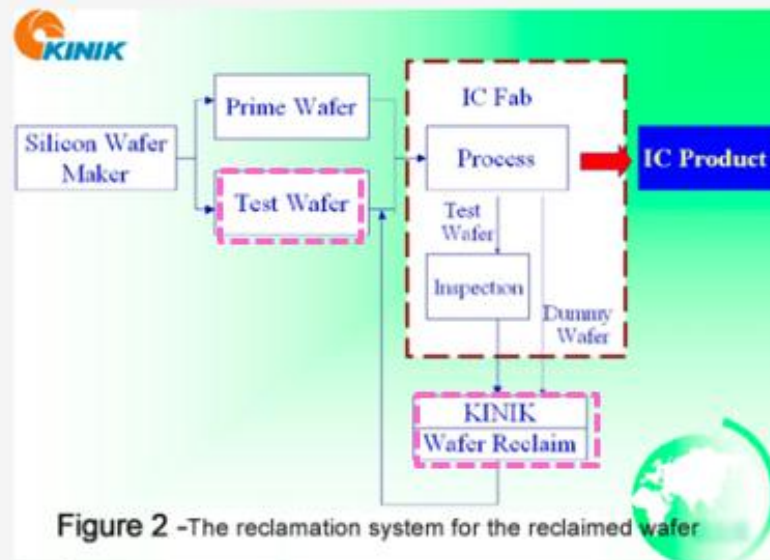
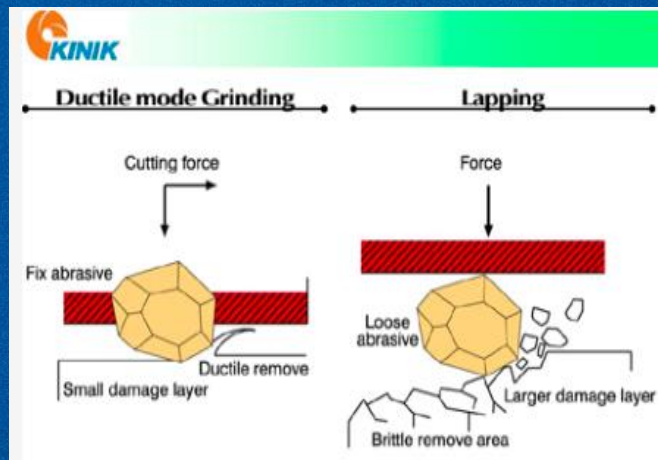


Figure 2 -The reclamation system for the reclaimed wafer

測試&再生晶圓 Test/Reclaim Wafer

中砂的再生晶圓之製程特色以延性輪磨(Ductile Mode Grinding)加工取代傳統研磨(Lapping)加工，目的是降低加工之變質層，減少化學藥品污染，且可提高加工精度，為最先進之再生晶圓製程。

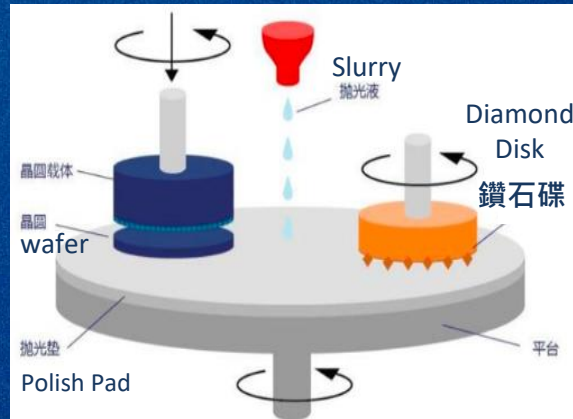
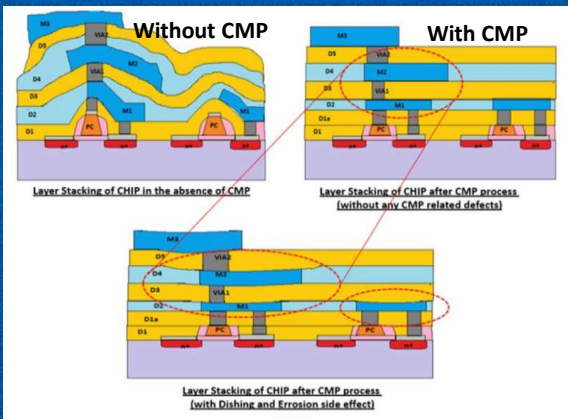
The features of the KINIK reclaimed wafers are refurbished by ductile mode grinding used to replace traditional lapping to lower the strained thickness on the surface and chemical contamination. The ductile mode grinding is the leading-edge process for the high precious reclaimed wafers.



CMP 鑽石碟 Diamond Disk

CMP (Chemical Mechanical Polish) 化學機械拋光，主要用於先進IC製程中，透過拋光墊與拋光液同時透過機械與化學反應加工晶圓表面，達到表面晶圓材料的移除及整體的平坦化，才能接續後續製程以及提高良率，進而能循摩爾定律持續微縮IC線寬面積，推展出N5/N3/N2先進製程。而**鑽石碟**的功用就是在拋光晶圓的同時去加工拋光墊，以移除拋光時的副產物及穩定拋光速率並提升良率及延長拋光墊使用壽命，是先進IC拋光製程中提升良率及控制成本中非常重要的一環。

CMP (Chemical Mechanical Polish) is widely used for advanced IC manufacturing processes for surface material removal, smoothing surfaces, and planarization by the polish pad (mechanical) and the abrasive slurry (chemical reaction). And the **diamond disk (aka pad conditioner)**'s function is to in-situ dress the polish pad during the process to remove the polish byproduct, to maintain a stable pad roughness and remove rate, to improve yield, and to prolong the lifetime of the pad.





CMP 鑽石碟 Diamond Disk

中砂鑽石碟用於半導體化學機械研磨製程中修整研磨墊以達到理想移除率及平坦度。

KINIK diamond disk is used on semi-conductor CMP process in order to make the pad reach the desirable removal rate and uniformity.

Conventional Disk



DiaGrid®

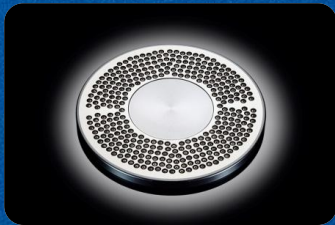


I-DiaGrid®



S-DiaGrid®

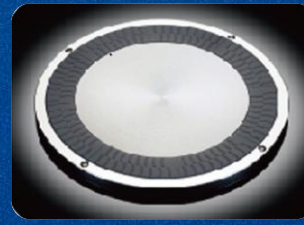
Advanced Disk : High Performance / Long Life Time



Pyradia®



EDP Disk
(Metal Free)



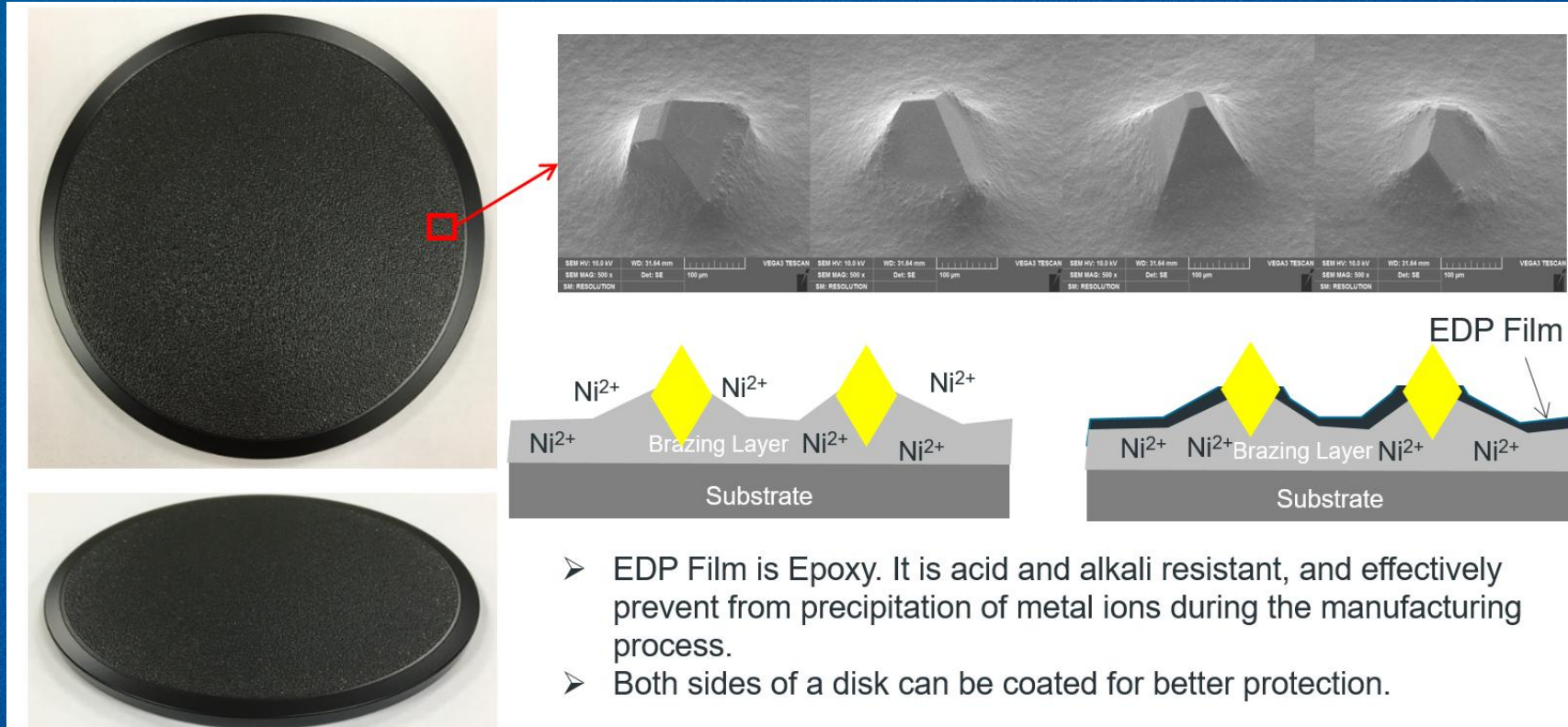
CVD -WAVE



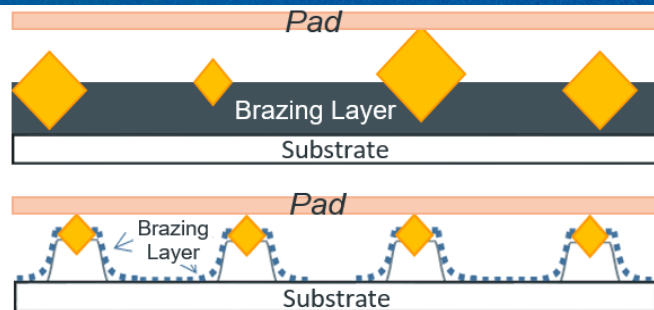
equaDia

EDP Disk for Metal Free Solution

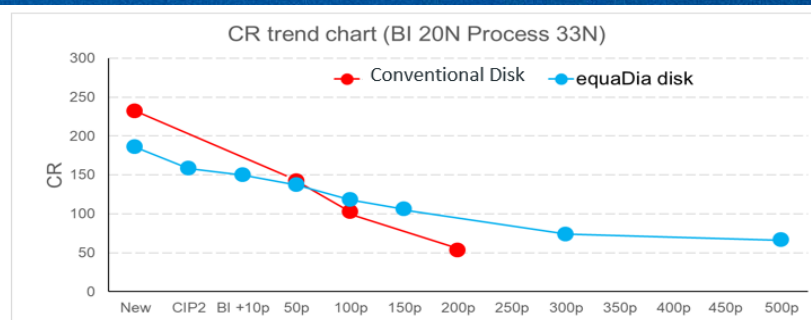
- Diamond disk protected with EDP film for metal-free requested in advanced IC technologies.



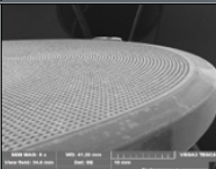
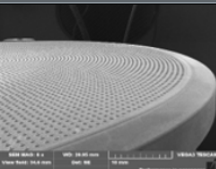
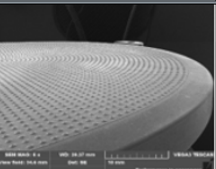
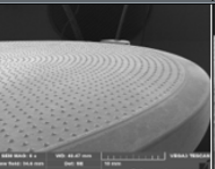
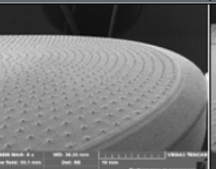
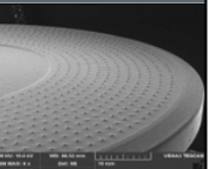
- Advanced disk “equaDia” for excellence tip height leveling and longer lifetime.



- Conventional Disk dressed a pad with the high points of the diamond. equaDia disk has good diamond leveling, and each diamond works. CR decay of equaDia disk is much slower.



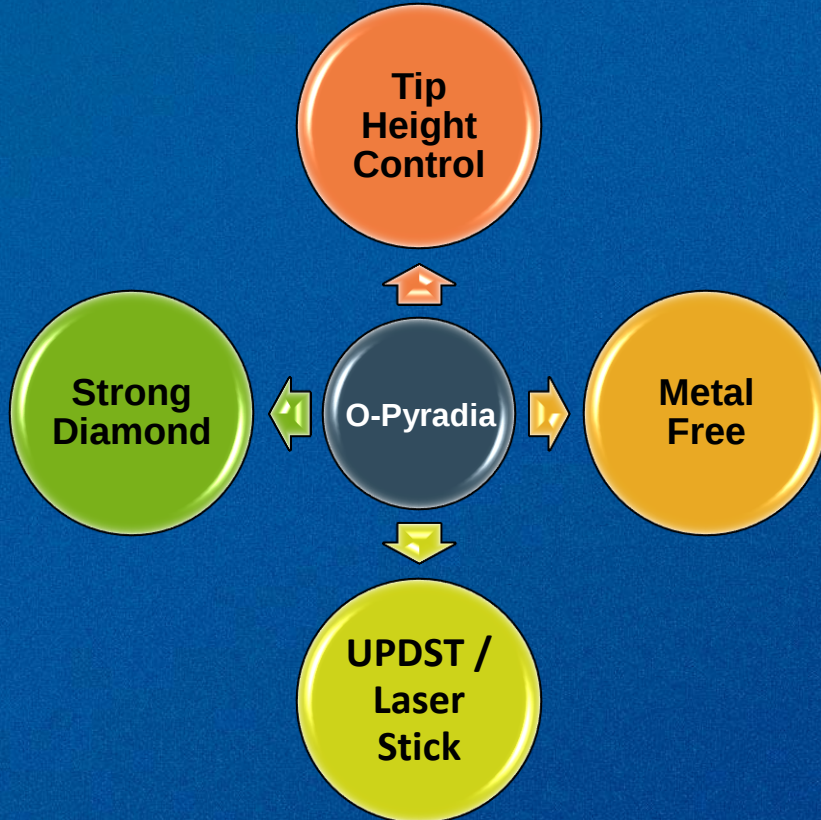
CR decay rate	100p	200p	300p	500p
Conventional Disk	56%	77%	-	-
equaDia disk	25%	-	54%	58%

	equaDia P800	equaDia P1000	equaDia P1200	equaDia P1500	equaDia P2000	equaDia P2000
SEM						
Appearance	Full face	Full face	Full face	Full face	Full face	Donut type
Diamond Size (μm)	100	100	100	100	170	170
Diamond pitch (μm)	800	1000	1200	1500	2000	2000
Diamond Bonded (%)	55%	53%	56%	51%	53%	55%
Leveling (μm)	6.9	7.2	7.6	6.7	9.7	9.9
total diamond count (ea)	11600	7450	5200	3350	1900	1400



Metal-free O-Pyradia® 鑽石碟

- O-Pyradia CMP pad conditioner for advanced customer's tightened metal contamination control.



Pyradia Type	O-Pyradia	Pyradia
Photo		
Material of Substrate	Polymer	Metal
Bonding Material	Polymer	LM(Ni ; Cr powder)
Bonding Strength	+	++
Process Temp	<100 degree	~1000 degree
Diamond Strength	++	+
Acid and alkali resistant	Metal Free	Ni ; Cr

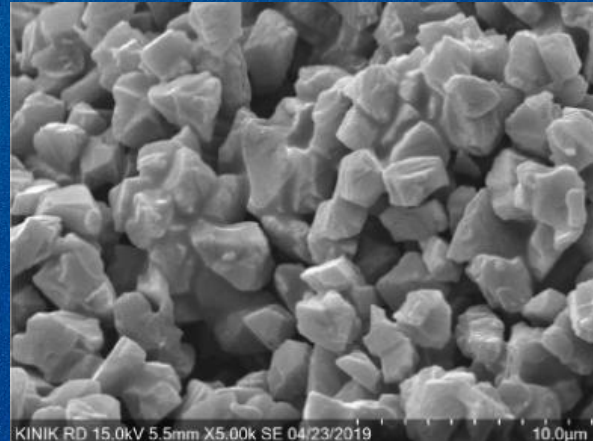


Semiconductor Grinding Wheel

- The Wafer grinding wheels are used in the in-feed grinding process of semiconductor wafers such as Si, SiC, and advanced 2.5D/3D package (Cu/compound...etc.). The in-feed grinding process consists of rough and fine grinding processes. Wafer grinding wheels are made of diamond abrasives and customized vitrified or resin bond in a unique porous microstructure. The diamond size for rough and finish grinding processes are #325~#1000 and #2000~#8000 respectively. The features of these wafer grinding wheels are stable high removal rate, long lifetime and lower grinding resistance.



Wafer Grinding Wheels



Porous microstructure

Diamond Roller

- The diamond rollers are used to sophisticatedly dress the complex and high precision form of grinding wheels (e.g. Al_2O_3 , SiC , cBN wheels) for automatic shaping high volume production of high precision transmission components such as ball screws, guides, bearings, gears, tools, automotive and aerospace parts etc..
- Diamond rollers are mainly made by reverse-plated or infiltration methods using natural, synthetic diamond grits or CVD diamond either randomly or regularly distributed. The features of the diamond rollers are high profile accuracy and high dressing efficiency. We can supply proper diamond rollers for grinders in various applications in accordance with customers need.



Diamond roller for
dressing profile
grinding wheel of
ball screw



Tools for Semiconductor & photoelectric

中砂以最新電鑄、成型與燒結技術製造成的精密鑽石切割刀。搭配特殊的金屬與樹脂等結合劑，使切割軟刀具備高剛性、低磨耗且具備良好的自銳性；適合在各類精密陶瓷、硬脆材料、磁性材料，光學玻璃，印刷電路板與半導體封裝材料的切割應用。

KINIK Company announces the introduction of Super Hubless Dicing Blade with resin, metal and nickel matrices. The dicing blades are manufactured by specialty consolidation, sintering and electro-forming process that improve the uniformity of the thin blades. They are suitable for cutting ceramics, brittle materials, optical glass, printed circuit boards, especially for semiconductor packaging.



鑽石切割軟刀 Dicing Blade



磨刀板 Dressing Board



Tools for Semiconductor & photoelectric

多孔質陶瓷真空吸盤

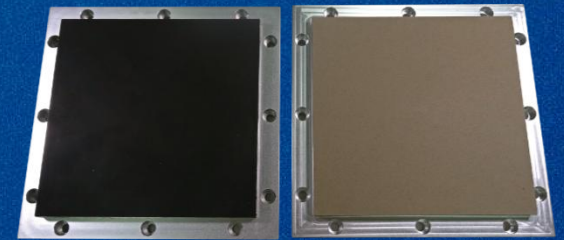
Porous Ceramic Chuck Table

多孔質陶瓷孔洞均勻微細、不發塵、可具靜電消散特性，應用於真空吸盤具備吸力均勻、局部吸附性、不產生印痕、工作效率及精度高等優點，可充分應用於半導體研磨、清洗、切割及檢測等設備。

- High-performance, High-precision, Uniform suction force.
- Partial chucking without sagging.
- Chucking and transport of wafer without leaving suction marks.
- Produces no static electricity and dust.

Application :

Wafer grinder, cleaning/dicing machine and measuring equipment, etc.





金屬精密加工刀具

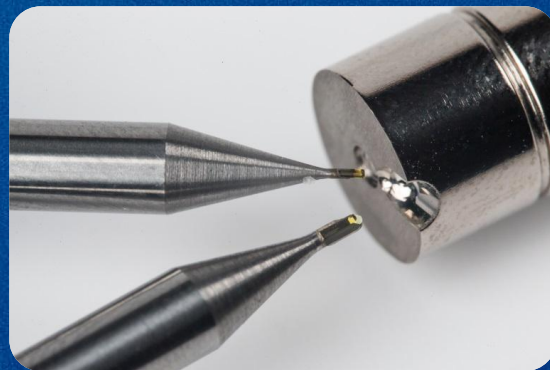
Ultra Precision Machining Tools

中砂提供電子業、PCB板、木工業及金屬加工業所需的單晶（SCD）、聚晶鑽（PCD）、立方氮化硼（PcBN）等鑽石刀具已逾20年。

近年積極投入生產高精度、更微小之SCD、PCD 及 PcBN產品供光學業、精密模具等加工技術使用，如：單晶鑽石車刀與銑刀、PcBN微小徑銑刀等。

KINIK company already has more than 20-year experience in providing all kinds of diamond tools for the applications of PCB, woodworking and metal working industries.

Recently, KINIK also developed several kinds of SCD, PCD and PcBN precision micro tools to meet high-end market's requirements.



加工面達到極高的光潔度表現。
High finish at processing parts.



傳統砂輪及鑽石/CBN砂輪

Traditional Grinding Wheel & Diamond / CBN Grinding Wheel

中砂提供各式平面、內外圓、無心及雙平面等工件研磨及切斷用的傳統、BD及電鑄砂輪。

主要產業應用包含精密機械業的滑軌及齒輪研磨與砂輪成形修整用的鑽石滾輪、鋼鐵業的軋筒研磨、工具製造業的高速鋼鑽頭、CNC及PCD/PcBN刀具等研磨、半導體業的晶圓減薄及倒角研磨、高效率硬脆材料如SiC研磨用的蜂巢砂輪、光學模具模仁拋光等。

KINIK provides various grinding wheels for surface, internal & cylindrical, centerless and disc surface grinding and cutting of workpiece production. The main industrial applications include linear guideway, gear grinding and diamond roller for dressing wheel in precision machinery, steel roll grinding, HSS drill, CNC & PCD/PcBN tool grinding, wafer thinning and edge grinding in semiconductor, honeycomb wheel for high-efficient grinding of hard and brittle materials such as SiC, optical mold polishing etc.

傳統砂輪及鑽石/CBN砂輪

Traditional Grinding Wheel & Diamond / CBN Grinding Wheel



平面研磨
Surface Grinding



外圓研磨
Cylindrical Grinding



輥筒研磨
Roll Grinding



滑軌成形研磨
Linear Guideway Grinding



雙平面研磨
Disc Surface Grinding



齒輪研磨
Gear Grinding



傳統砂輪及鑽石/CBN砂輪

Traditional Grinding Wheel & Diamond / CBN Grinding Wheel



光學模仁拋光
Optical Mold Polishing



內圓研磨
Internal Grinding



CNC刀具研磨
CNC Tools Grinding



蜂巢砂輪
Diamond & CBN Honey Comb Wheel



PCD刀具研磨
PCD Cutting Tools Grinding



傳統砂輪及鑽石/CBN砂輪

Traditional Grinding Wheel & Diamond / CBN Grinding Wheel



電鑄砂輪
Electroplated Diamond & CBN Wheels
and Products



各式切斷及可彎曲、碟式砂輪
Cut-off, Depressed & Flexible Wheels, and
Flap Disc



鑽石滾輪
Diamond Roller



砂輪動平衡校正儀
Grinder Balancer



廠區 Plant Information



總公司 Head Office 鶯歌廠區 Yingge Factory

239010 新北市鶯歌區中山路64號
No.64, Zhongshan Rd., Yingge Dist.,
New Taipei City 239010, Taiwan
TEL:+886 2 2679-1931~40

Grinding Wheel & Diamond Disk



樹林廠區 Shulin Factory

238010 新北市樹林區中山路2段151巷16號
No.16, Ln. 151, Sec. 2, Zhongshan Rd.,
Shulin Dist., New Taipei City 238010, Taiwan
TEL:+886 2 8684-4111~13

Diamond Disk
Diamond Cutting & Dicing Tools



新竹廠區 Hsinchu Factory

303035 新竹縣湖口鄉新竹工業區文化路6號
No.6, Wenhua Rd., Hukou, Hsinchu Ind.
Park, Hsinchu County 303035, Taiwan
TEL:+886 3 598-4990

Diamond Dicing Tools. PVD Coating
Ceramic Vacuum Chuck





廠區 Plant Information



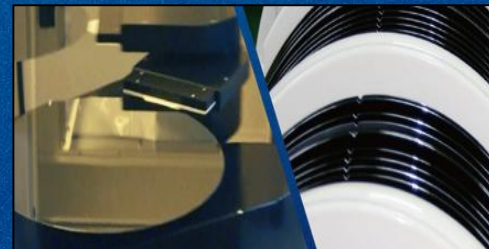
竹北廠區 Zhubei Factory

302059 新竹縣竹北市十興路260號
No.260, Shixing Rd., Zhubei City,
Hsinchu County 302059, Taiwan
TEL:+886 3 550-7160~5



竹科廠區 Hsinchu Science Park Factory

350401 苗栗縣竹南鎮科北五路6號
No. 6, Kebei 5th Rd., Jhunan
Township, Miaoli County 350401,
Taiwan
TEL:+886 3 550-7160



Reclaim & Test Wafer
再生晶圓 & 測試晶圓



廠區 Plant Information



鴻記工業股份有限公司

Hongia Industry Co, Ltd.

239008 新北市鶯歌區余厝巷2號
No. 2, Yucho Lane, Yingge Dist.,
New Taipei City 239008, Taiwan

TEL:+886 2 2679-1006

Email : hongia-sale@kinik.com.tw

www.hongia.com.tw



Electroplated Diamond
Wheel 電鑄砂輪



金力泰國有限公司

Kinik - Thai Co., Ltd.

225 Moo 7, Khok Pip, Simahosot,
Prachinburi 25190 Thailand
TEL:+663 727 6954

Email : sales@kinikthai.co.th

www.kinikthai.co.th



Resin and Ceramic Wheel
樹脂砂輪&陶瓷砂輪



Acquired MKS (Japan) & MGT (Thailand) as subsidiaries on April 2025



中砂KINIK 集團創業72周年慶 歡喜迎接新紀元

日本MKS 及 泰國MGT 公司正式加入，開創全球發展新篇章



中砂
報

活動日期：2025/04/01
出刊日期：2025/04/01

2025年4月1日，是中砂KINIK集團歡慶創業72周年的日子，同時也是集團迎來重要的里程碑——原在日本三井金屬工業集團旗下的日本MKS 公司和泰國的 MGT 公司 正式加入KINIK集團邁向全球化發展的新階段。

今天舉辦的正式收購交割及更名揭牌儀式標誌著 KINIK 集團在精密研磨與半導體材料研磨領域的全球擴張，並開啟了集團進一步提升技術創新和市場競爭力的嶄新篇章。

MKS、MGT 新名創新局

自2025年4月1日起，MKS 公司正式更名為 マックスキニック精密株式会社 (英文名稱:Max Kinik Seimitsu Co., Ltd.)，MGT公司更名為 Max Kinik Grinding Technology Co., Ltd.。

此次更名由 KINIK 集團股東提出，新名稱中的 "Max" 代表規模最大化，"Kinik" 承載著 KINIK 集團在研磨領域的專業精神，象徵著公司將專注於最大化其潛力及市場影響力。而 "Seimitsu" 及 "Grinding Technology" 則代表對精密加工技術的極致追求。MKS暨MGT社長坂井正博表示：「今天是我公司歷史中的一個重要時刻，作為 KINIK 集團的一員，我們將繼承百年來積累的技术實力與市場聲譽，並結合 KINIK 集團的全球資源，共同創造更多的發展機會。」

強化全球市場競爭力

此次MKS 和 MGT加入KINIK集團，不僅是KINIK集團對這兩家公司的肯定，更是集團邁向全球市場的重要步伐。KINIK集團林伯全董事長表示：「今天，MKS和MGT正式成為 KINIK 集團的一員，這不僅是KINIK集團對兩家公司過去努力的肯定，更是大家一起面對未來挑戰的新起點。我們將繼續傳承三井研削的卓越技術，並結合 KINIK 集團的資源，推動全球市場的拓展，不斷創新、挑戰行業的更高標準。」

跨越百年，凝聚力量創新發展，攜手磨出共好大未來

KINIK 集團謝榮哲執行長在致詞中指出：「砂輪產品雖然看似不起眼，但其在汽車、航空、機械加工及半導體等關鍵領域扮演著至關重要的角色。隨著 MKS和MGT的加入，KINIK集團在台灣、泰國、日本設有生產基地，在該三國及中國大陸設有營業單位，產品行銷全球五十多個國家，集團內公司將發揮彼此的技術優勢，提升品牌影響力，開創新的成長契機。」

謝執行長表示：「新公司名稱的揭牌象徵著新時代的開始。我們希望在擁有百年歷史的『MKS』優秀傳統基礎上，與各位共同發揮相互的優勢，建立互信關係，攜手邁向更美好的未來。今後，我們一起努力磨出共好大未來。」

共好：你好、我好、大家好！讓我們攜手磨出共好大未來！



榮耀記事 Milestone



2021年11月榮獲行政院「第26屆國家品質獎 全面卓越類 - 績優經營獎」。

Nov. 2021, Honored with "BUSINESS MERIT AWARD of Total BUSINESS EXCELLENCE" at the 26th NATIONAL QUALITY AWARD from the Executive Yuan, R.O.C.

https://nqa.cpc.tw/NQA/Web/Awards26th_Content.aspx?p=f2b6e812-92aa-49c3-8149-1e005a0fe706

賀!中國砂輪公司榮獲「第26屆國家品質獎」



經濟部 林全副委員長(左)、中國砂輪公司 林伯全董事長(右)。圖/經濟部工業局提供。

中國砂輪公司 榮獲「第26屆國家品質獎」，林伯全董事長受邀晉見總統



中國砂輪公司董事長 林伯全(右)、總統 蔡英文(左)。圖/總統府提供



2021年10月榮獲經濟部「2022年第30屆台灣精品獎 - 12吋再生晶圓」。

Oct. 2021, Honored with "Taiwan Excellence Award - 12" Reclaimed Wafers" from the MOEA, R.O.C.

<https://www.taiwanexcellence.org/tw/award/product/1110433>



TAIWAN EXCELLENCE

得獎產品：12 inches Reclaim Wafer



榮獲經濟部第四屆卓越中堅企業獎

Honored with 4th Taiwan mittelstand Award from the MOEA, R.O.C, in 2017.



榮獲經濟部2013年 第14屆 工業精銳獎 機械、運輸工業類

Honored with 14th Industrial Sustainable Excellence Award from the MOEA, R.O.C, in 2013.

TOP 100
TAIWAN BRANDS



榮獲經濟部台灣百大品牌獎

Honored with the Top 100 Taiwan Brands Award from the MOEA, R.O.C, in 2011.



榮獲經濟部2006年台灣優良品牌獎

Honored with the Taiwan Superior Brand Award from the MOEA, R.O.C, in 2006.



榮獲第十屆經濟部產業科技發展傑出獎

Award of Excellence, the 10th R.O.C. MOEA Industrial Technology Advancement Award in 2002.



全國第一家砂輪公司榮獲國家傑出精品獎

The first grinding wheel plant won Excellent Product Award in 1993.